HMC492LP3 / 492LP3E

v04.0507

SMT GaAs HBT MMIC
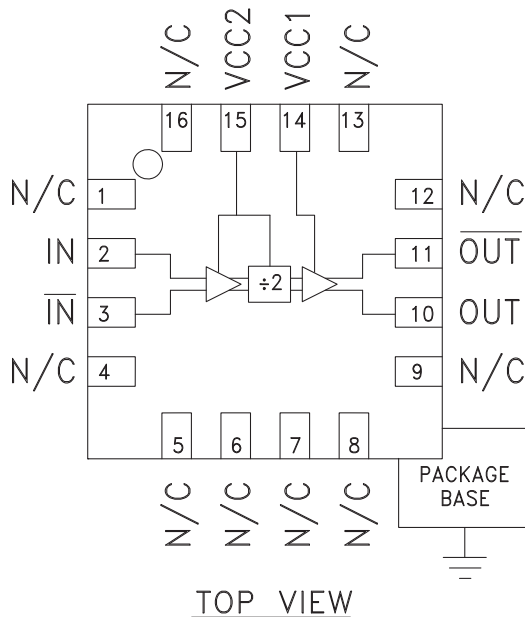## DIVIDE-BY-2, DC - 18 GHz

Typical Applications

Prescaler for DC to 18 GHz PLL Applications:

• Point-to-Point / Multi-Point Radios

• VSAT Radios

• Fiber Optic

• Test Equipment

• Military

Features

Ultra Low SSB Phase Noise: -150 dBc/Hz

Very Wide Bandwidth

Output Power: -4 dBm

Single DC Supply: +5V

3x3 mm QFN SMT Package

Functional Diagram

TOP VIEW

General Description

The HMC492LP3 & HMC492LP3E are low noise Divide-by-2 Static Dividers utilizing InGaP GaAs HBT technology packaged in leadless 3x3 mm QFN surface mount plastic packages. This device operates from DC (with a square wave input) to 18 GHz input frequency from a single +5V DC supply. The low additive SSB phase noise of -150 dBc/Hz at 100 kHz offset helps the user maintain excellent system noise performance.

Electrical Specifications, T_A = +25° C, 50 Ohm System, Vcc= +5V

Parameter	Conditions	Min.	Typ.	Max.	Units
Maximum Input Frequency		18	19		GHz
Minimum Input Frequency	Sine Wave Input. [1]		0.2	0.5	GHz
Input Power Range	Fin = 2 to 14 GHz	-20	-15	+10	dBm
	Fin = 14 to 16 GHz	-20	-15	+5	dBm
	Fin = 16 to 18 GHz	-15	-10	0	dBm
Output Power	Fin = 0.5 to 18 GHz	-7	-4		dBm
Reverse Leakage	Both RF Outputs Terminated		60		dB
SSB Phase Noise (100 kHz offset)	Pin = 0 dBm, Fin = 4.8 GHz		-150		dBc/Hz
Output Transition Time	Pin = 0 dBm, Fout = 882 MHz		100		ps
Supply Current (Icc1 + Icc2)			78		mA

1. Divider will operate down to DC for square-wave input signal

HMC492* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- HMC492LP3 Evaluation Board

DOCUMENTATION

Data Sheet

- HMC492 Data Sheet

REFERENCE MATERIALS

Quality Documentation

- Package/Assembly Qualification Test Report: 16L 3x3mm QFN Package (QTR: 11003 REV: 02)
- Package/Assembly Qualification Test Report: LP2, LP2C, LP3, LP3B, LP3C, LP3D, LP3F, LP3G (QTR: 2014-0364)
- Package/Assembly Qualification Test Report: Plastic Encapsulated QFN (QTR: 05006 REV: 02)
- Semiconductor Qualification Test Report: GaAs HBT-A (QTR: 2013-00228)

DESIGN RESOURCES

- HMC492 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC492 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.

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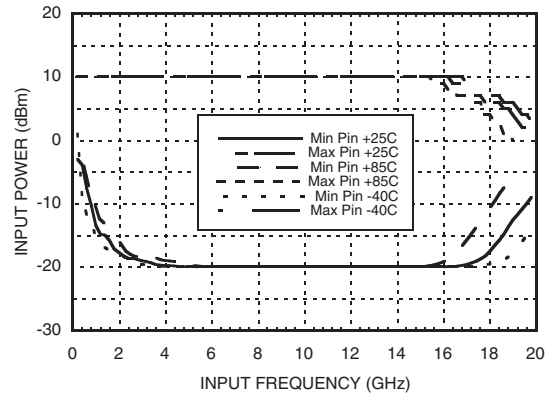
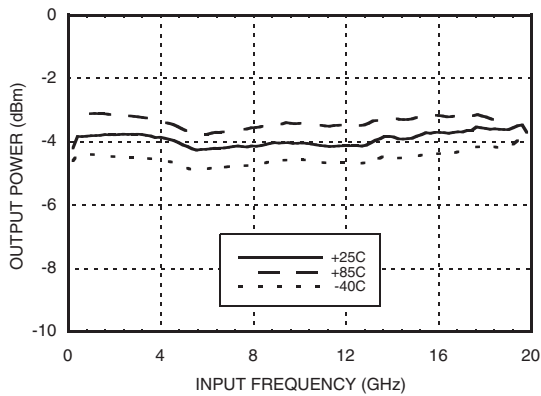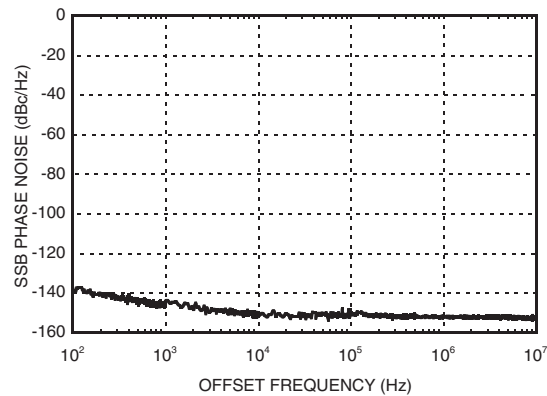*Input Sensitivity Window, T= 25 °C*
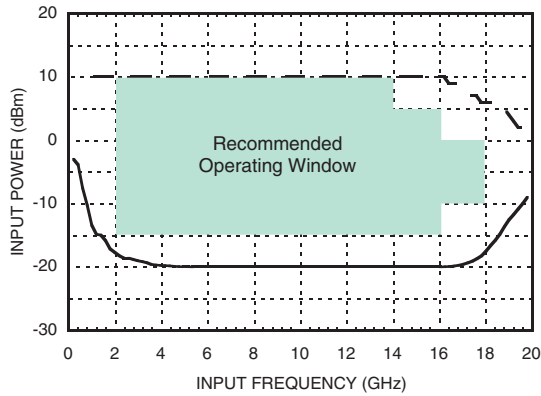
Input Sensitivity Window vs. Temperature

Output Power vs. Temperature

SSB Phase Noise Performance,
Pin= 0 dBm, T= 25 °C

Output Harmonic Content,
Pin= 0 dBm, T= 25 °C
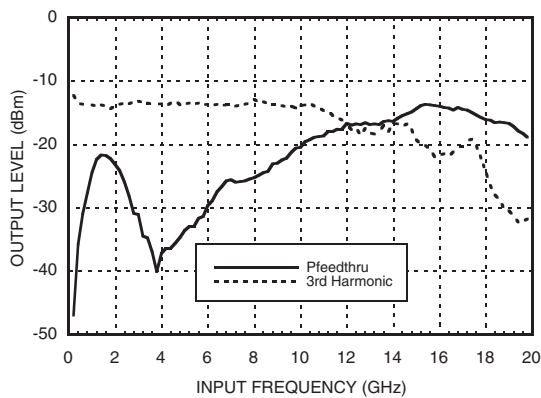
Reverse Leakage, Pin= 0 dBm, T= 25 °C

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DIVIDE-BY-2, DC - 18 GHz

Output Voltage Waveform, Pin= 0 dBm, Fout= 882 MHz, T= 25 °C

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS
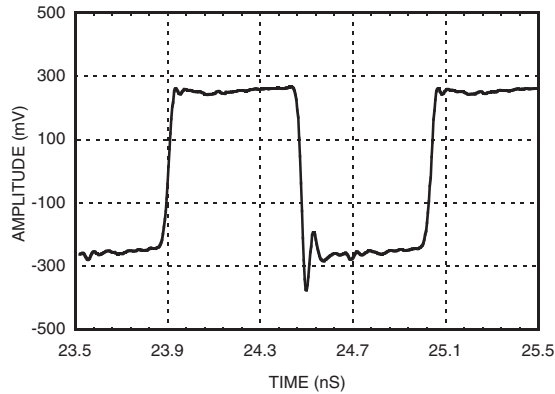
Absolute Maximum Ratings

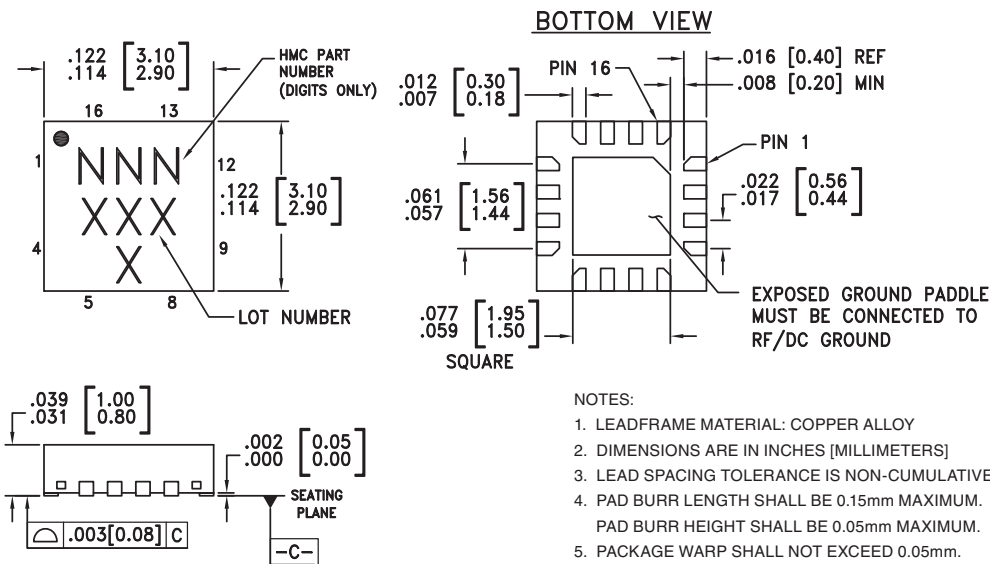|	
RF Input (Vcc = +5V)	+13 dBm
Supply Voltage (Vcc1, Vcc2)	+5.5V
Channel Temperature (Tc)	135 °C
Continuous Pdiss (T = 85 °C) (derate 11.9 mW/° C above 85 °C)	593 mW
Storage Temperature	-65 to +150 °C
Thermal Resistance (R_{TH}) (junction to ground paddle)	84 °C/W
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

Typical Supply Current vs. Vcc

Vcc1, Vcc2 (V)	Icc (mA)
4.75	69
5.0	78
5.25	87

Note: Divider will operate over full voltage range shown above

Outline Drawing

NOTES:
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.
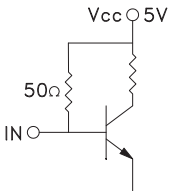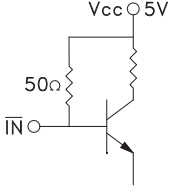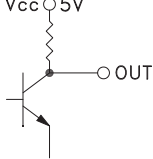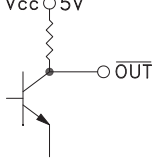
Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC492LP3	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	492 XXXX
HMC492LP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	492 XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX

For price, delivery, and to place orders: Analog Devices, Inc., One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106 Phone: 781-329-4700 • Order online at www.analog.com Application Support: Phone: 1-800-ANALOG-D

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RoHS✓

EARTH FRIENDLY

Pin Description

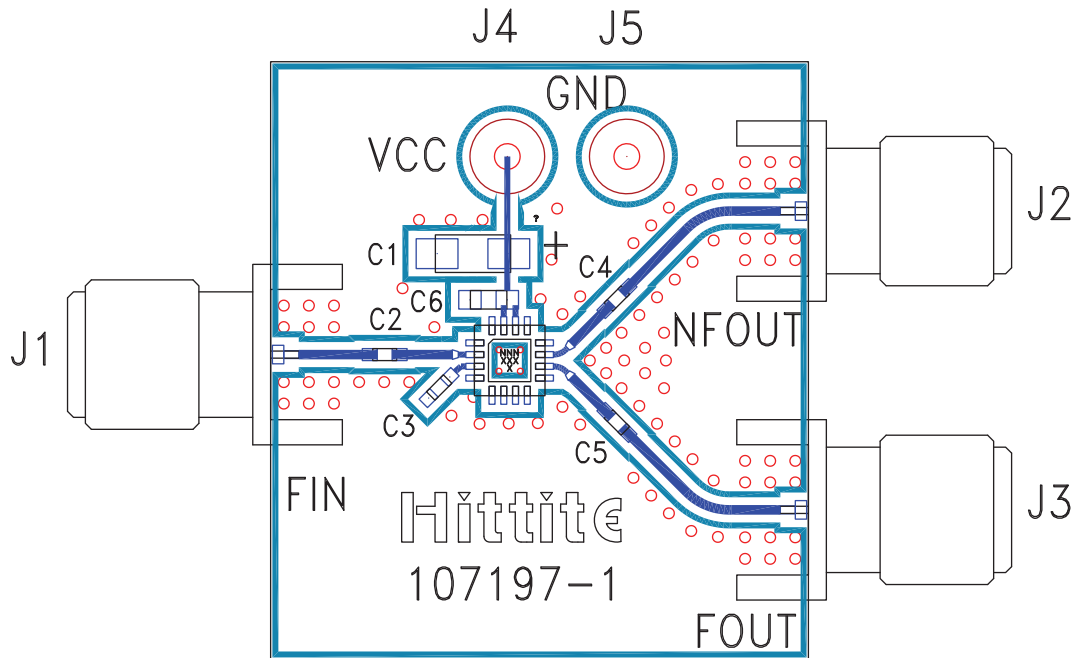| Pin Number	Function	Description	Interface Schematic
1, 4-9, 12, 13, 16	N/C	No connection.	
2	IN	RF Input must be DC blocked.	Vcc 5V 50Ω IN
3	$\overline{IN}$	RF Input 180° out of phase with pin 2 for differential operation. AC ground for single ended operation.	Vcc 5V 50Ω $\overline{IN}$
10	OUT	Divided Output.	Vcc 5V OUT
11	$\overline{OUT}$	Divided output 180° out of phase with pin 10.	Vcc 5V $\overline{OUT}$
14, 15	Vcc1, Vcc2	Supply voltage 5V ± 0.25V. Connect both pins to +5V supply.	
	GND	Ground: Backside of package has exposed metal ground slug which must be connected to RF/DC ground.	GND

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Evaluation PCB

List of Materials for Evaluation PCB 107384 [1]

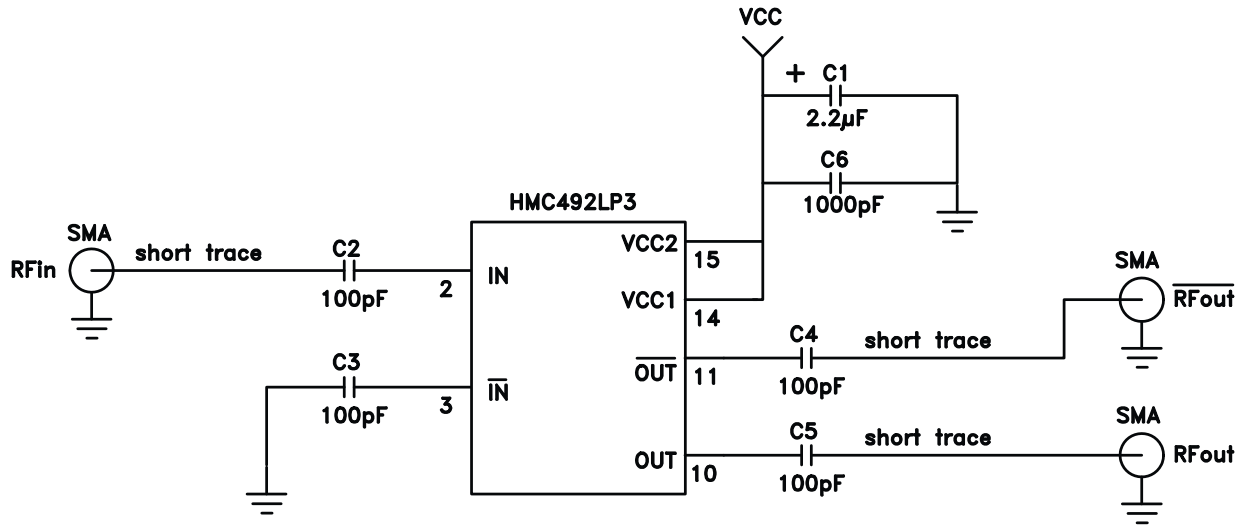| Item	Description
J1 - J3	PCB Mount SMA RF Connector
J4, J5	DC Pin
C2 - C5	100 pF Capacitor, 0402 Pkg.
C6	1000 pF Capacitor, 0603 Pkg.
C1	2.2 uF Tantalum Capacitor
U1	HMC492LP3 / HMC492LP3E Divide-by-2
PCB [2]	107197 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request. This evaluation board is designed for single ended input testing. J2 and J3 provide differential output signals.

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6

Application Circuit